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(54) **LIGHT EMITTING DEVICE PACKAGE, WAVELENGTH CONVERSION FILM, AND MANUFACTURING METHOD THEREOF**

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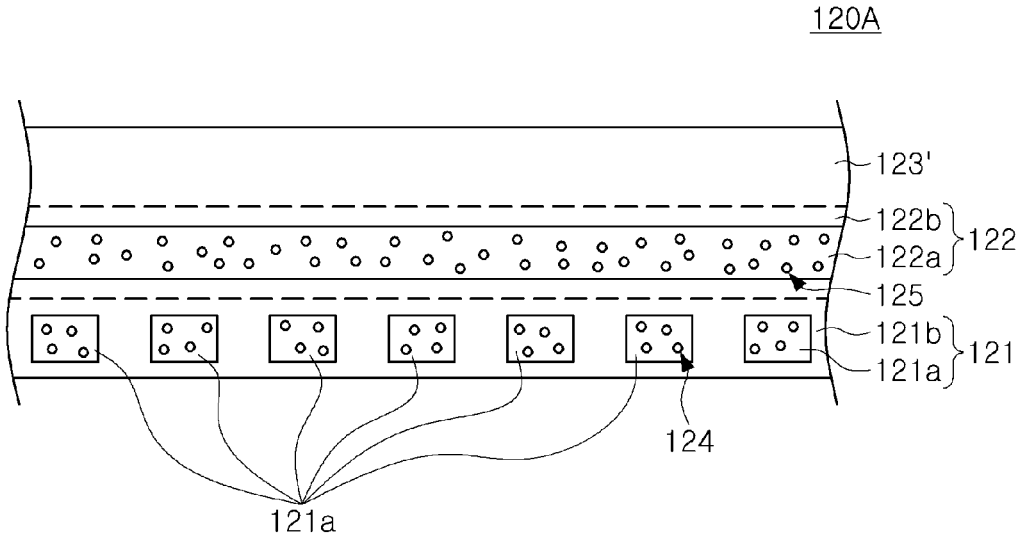
(57) **ABSTRACT**

A light emitting device package is provided. The package includes a light emitting device including a substrate, and a light emitting structure having a first conductivity-type semiconductor layer, an active layer, and a second conductivity-type semiconductor layer stacked on the substrate; and a wavelength conversion film disposed in a path of light emitted by the light emitting device and having phosphor layers stacked on each other. A portion of the phosphor layers includes phosphor structures including a wavelength conversion material receiving light emitted from the light emitting device and converting a wavelength thereof and a binding resin binding the wavelength conversion material, and a transparent resin filling spaces between the phosphor structures.

19 Claims, 26 Drawing Sheets